



### Electrical Performance

Parameter	Min.	Typ.	Max.	Units	Notes
Output frequency	1.8432		106.25	MHz	As specified
Supply voltage	+3.135	+3.3	+3.465	V	
Supply current, output enabled			10	mA	1.8432 to 50 MHz
			18		>50 MHz
Supply current, standby mode			10	μA	Output Hi-Z
Frequency stability			±25 to ±50	ppM	See Note 1 below
Operating temperature	-40		+85	°C	As specified
Output logic 0, VOL			10% V <sub>DD</sub>	V	I <sub>OL</sub> = 4mA min
Output logic 1, VOH	90% V <sub>DD</sub>			V	I <sub>OH</sub> = -4mA max
Output load			15	pF	
Duty cycle	45		55	%	-40 to +85°C measured 50%V <sub>DD</sub>
Rise and fall time			5	ns	measured 10/90% of waveform
Jitter, Phase	up to 75 MHz		1.5	ps RMS (1-σ)	10kHz to 20 MHz frequency band
	75 to 100 MHz		1		
Jitter, Accumulated	up to <75 MHz		5	ps RMS (1-σ)	20.000 adjacent periods
	75 to 100 MHz		3		
Jitter, Total	up to <75 MHz		50	ps pk-pk	100.000 random periods
	75 to 100 MHz		30		

#### Notes:

- As specified. Stability includes all combinations of operating temperature, load changes, rated input (supply) voltage changes, initial calibration tolerance (25°C), aging (1 year at 25°C average effective ambient temperature), shock and vibration.
- Note: For specifications other than those listed, please contact sales.

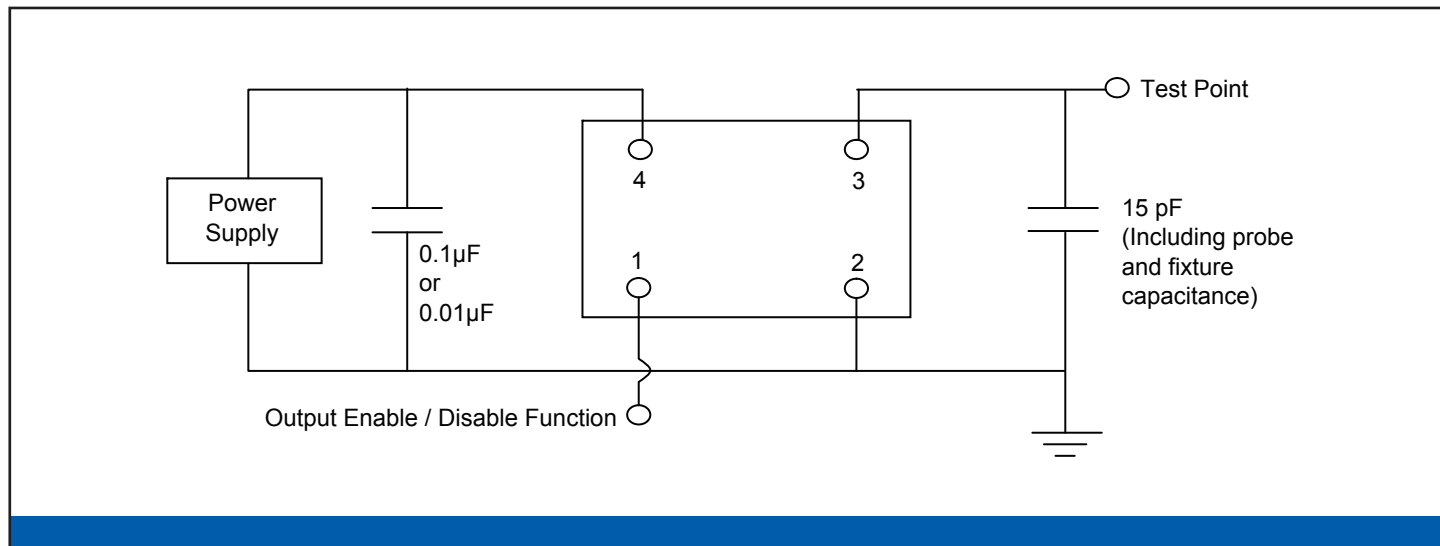
### Output Enable / Disable Function

Parameter	Min.	Typ.	Max.	Units	Notes
Input Voltage (pin 1), Output Enable	0.7V <sub>DD</sub>			V	or open
Input voltage (pin 1), Output Disable (low power standby)			0.3V <sub>DD</sub>	V	Output is Hi-Z
Internal pullup resistance	30			kΩ	
Output disable delay			100	ns	
Output enable delay			10	ms	

## Absolute Maximum Ratings

Parameter	Min.	Typ.	Max.	Units	Notes
Storage temperature	-55		+125	°C	

## Test Circuit

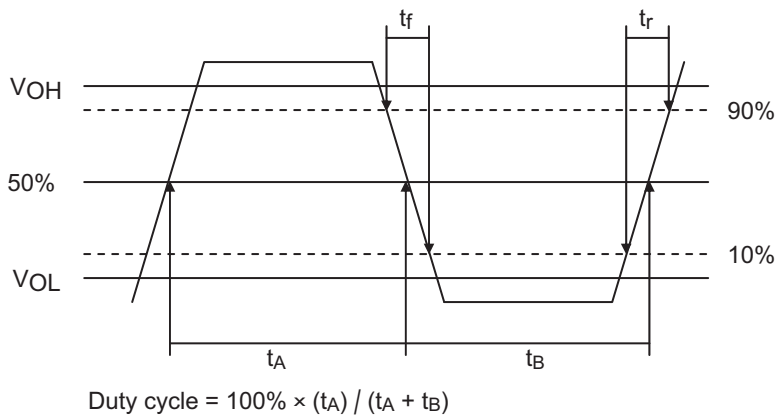


## Reliability Test Ratings

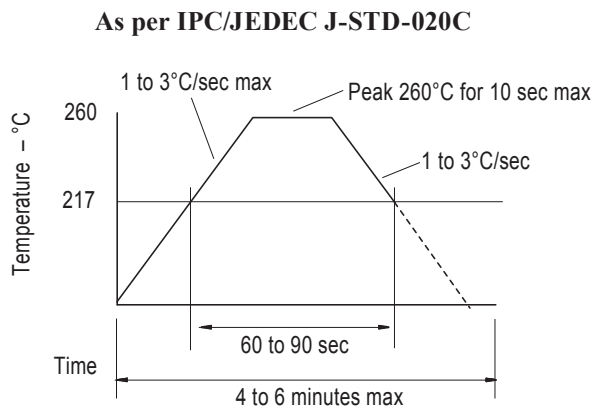
This product is rated to meet the following test conditions:

Type	Parameter	Test Condition
Mechanical	Shock	MIL-STD-883, Method 2002, Condition B
Mechanical	Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Mechanical	Terminal strength	MIL-STD-883, Method 2004, Condition D
Mechanical	Gross leak	MIL-STD-883, Method 1014, Condition C
Mechanical	Fine leak	MIL-STD-883, Method 1014, Condition A2 ( $R_1 = 2 \times 10^{-8}$ atm cc/s)
Mechanical	Solvent resistance	MIL-STD-202, Method 215
Environmental	Thermal shock	MIL-STD-883, Method 1011, Condition A
Environmental	Moisture resistance	MIL-STD-883, Method 1004
Environmental	Vibration	MIL-STD-883, Method 2007, Condition A
Environmental	Resistance to soldering heat	J-STD-020C Table 5-2 Pb-free devices (2 cycles max)

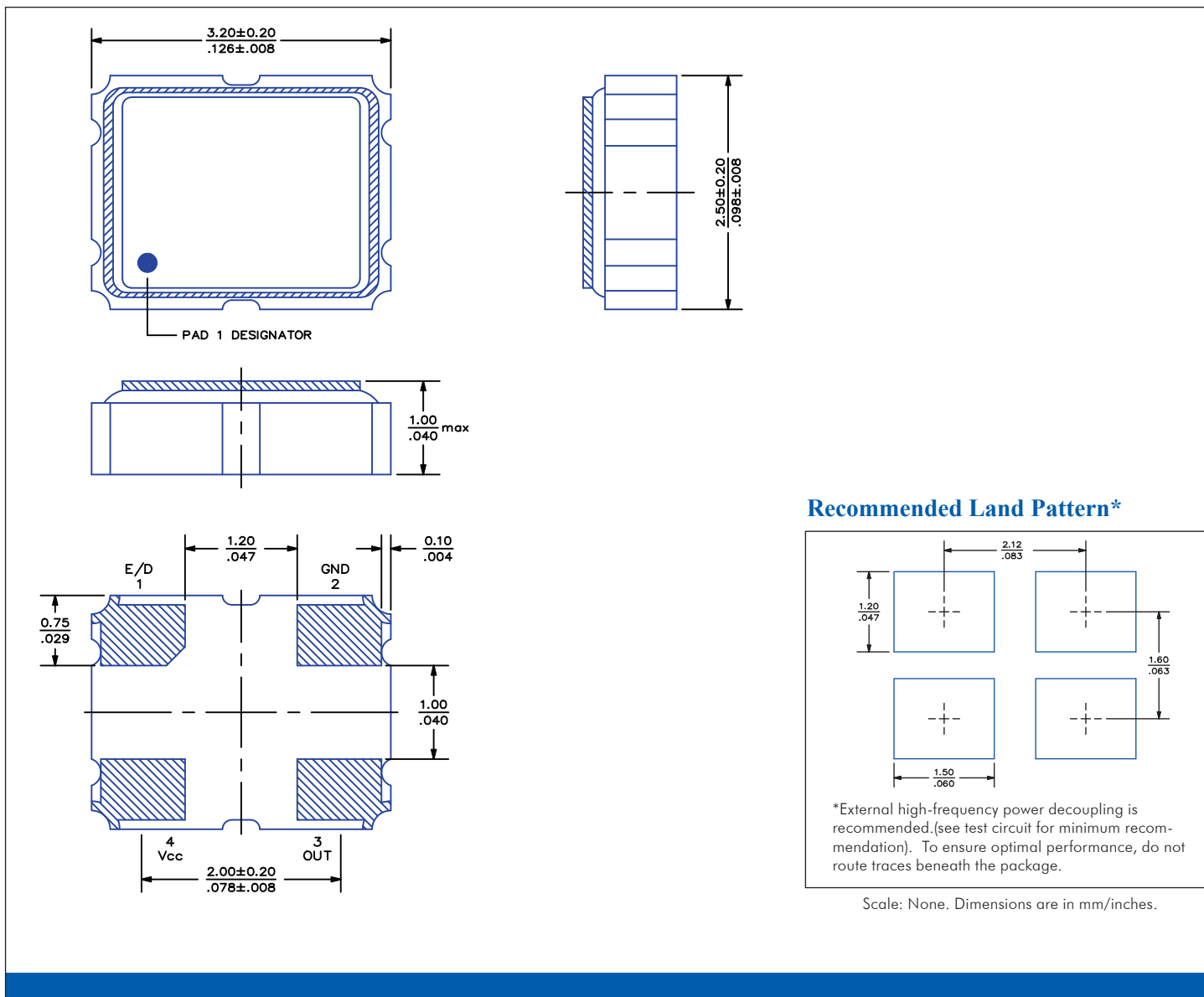
## Output Waveform



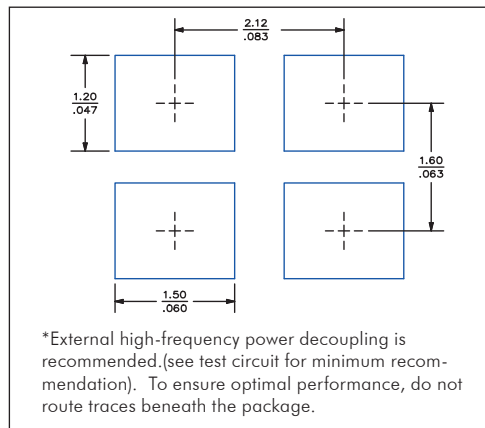
## Reflow Soldering Profile



## Mechanical Drawings



## Recommended Land Pattern\*



\*External high-frequency power decoupling is recommended. (see test circuit for minimum recommendation). To ensure optimal performance, do not route traces beneath the package.

Scale: None. Dimensions are in mm/inches.